

# International Rectifier

"HALF-BRIDGE" IGBT DOUBLE INT-A-PAK

PD - 50048C

## GA500TD60U

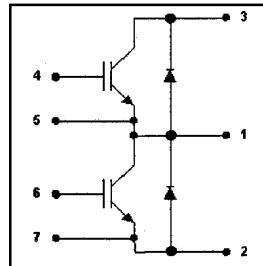
Ultra-Fast™ Speed IGBT

### Features

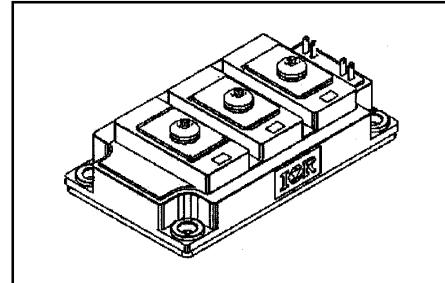
- Generation 4 IGBT technology
- UltraFast: Optimized for high operating frequencies 8-40 kHz in hard switching, >200 kHz in resonant mode
- Very low conduction and switching losses
- HEXFRED™ antiparallel diodes with ultra- soft recovery
- Industry standard package
- UL approved

### Benefits

- Increased operating efficiency
- Direct mounting to heatsink
- Performance optimized for power conversion: UPS, SMPS, Welding
- Lower EMI, requires less snubbing



$V_{CES} = 600V$
$V_{CE(on)} \text{ typ.} = 1.9V$
@ $V_{GE} = 15V, I_C = 500A$



### Absolute Maximum Ratings

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ\text{C}$	Continuous Collector Current	500	
$I_{CM}$	Pulsed Collector Current①	1000	A
$I_{LM}$	Peak Switching Current②	1000	
$I_{FM}$	Peak Diode Forward Current	500	
$V_{GE}$	Gate-to-Emitter Voltage	$\pm 20$	V
$V_{ISOL}$	RMS Isolation Voltage, Any Terminal To Case, $t = 1 \text{ min}$	2500	
$P_D @ T_C = 25^\circ\text{C}$	Maximum Power Dissipation	1550	W
$P_D @ T_C = 85^\circ\text{C}$	Maximum Power Dissipation	800	
$T_J$	Operating Junction Temperature Range	-40 to +150	°C
$T_{STG}$	Storage Temperature Range	-40 to +125	

### Thermal / Mechanical Characteristics

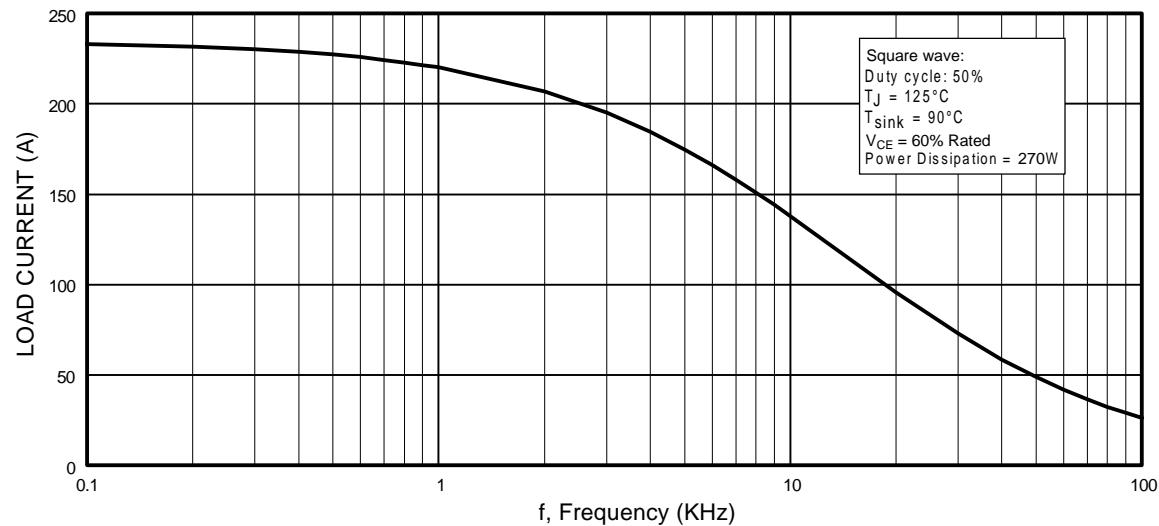
	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case - IGBT	—	0.08	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case - Diode	—	0.20	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink - Module	0.1	—	
	Mounting Torque, Case-to-Heatsink	—	4.0	N·m
	Mounting Torque, Case-to-Terminal 1, 2 & 3f	—	3.0	
	Weight of Module	400	—	g

**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

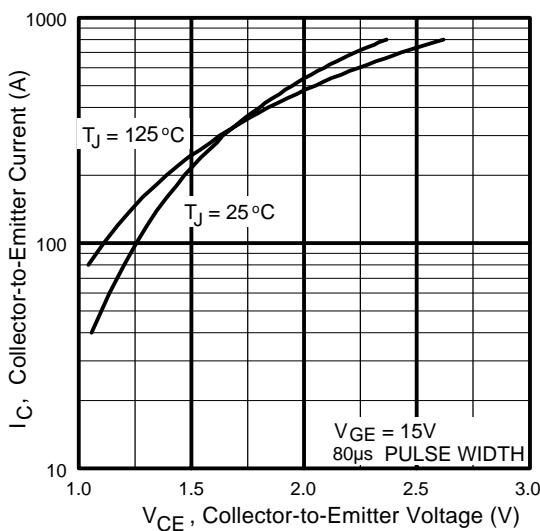
	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{CES}}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	$V_{\text{GE}} = 0\text{V}, I_C = 1\text{mA}$
$V_{\text{CE}(\text{on})}$	Collector-to-Emitter Voltage	—	1.9	2.4		$V_{\text{GE}} = 15\text{V}, I_C = 500\text{A}$
		—	2.0	—		$V_{\text{GE}} = 15\text{V}, I_C = 500\text{A}, T_J = 125^\circ\text{C}$
$V_{\text{GE}(\text{th})}$	Gate Threshold Voltage	3.0	—	6.0		$I_C = 3.0\text{mA}$
$\Delta V_{\text{GE}(\text{th})}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/°C	$V_{\text{CE}} = V_{\text{GE}}, I_C = 3.0\text{mA}$
$g_{\text{fe}}$	Forward Transconductance ④	—	244	—	S	$V_{\text{CE}} = 25\text{V}, I_C = 500\text{A}$
$I_{\text{CES}}$	Collector-to-Emitter Leaking Current	—	—	2.0	mA	$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}$
		—	—	20		$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}, T_J = 125^\circ\text{C}$
$V_{\text{FM}}$	Diode Forward Voltage - Maximum	—	4.0	—	V	$I_F = 500\text{A}, V_{\text{GE}} = 0\text{V}$
		—	4.1	—		$I_F = 500\text{A}, V_{\text{GE}} = 0\text{V}, T_J = 125^\circ\text{C}$
$I_{\text{GES}}$	Gate-to-Emitter Leakage Current	—	—	250	nA	$V_{\text{GE}} = \pm 20\text{V}$

**Dynamic Characteristics -  $T_J = 125^\circ\text{C}$  (unless otherwise specified)**

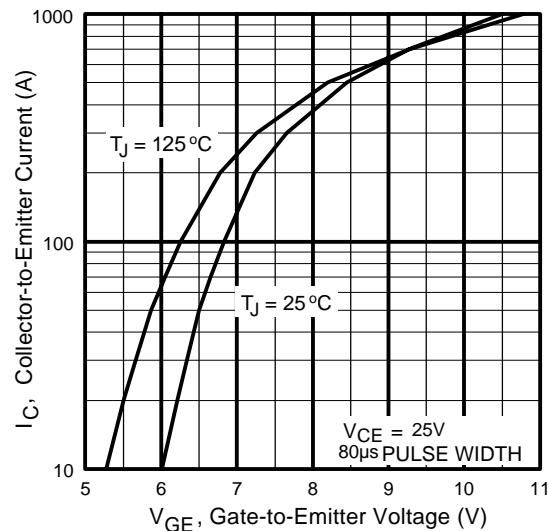
	Parameter	Min.	Typ.	Max.	Units	Conditions
$Q_g$	Total Gate Charge (turn-on)	—	2100	3200	nC	$V_{\text{CC}} = 400\text{V}$
$Q_{ge}$	Gate - Emitter Charge (turn-on)	—	292	440		$I_C = 500\text{A}$
$Q_{gc}$	Gate - Collector Charge (turn-on)	—	1050	1580		$T_J = 25^\circ\text{C}$
$t_{d(\text{on})}$	Turn-On Delay Time	—	1900	—	ns	$R_{G1} = 15\Omega, R_{G2} = 0\Omega,$ $I_C = 500\text{A}$
$t_r$	Rise Time	—	430	—		$V_{\text{CC}} = 360\text{V}$
$t_{d(\text{off})}$	Turn-Off Delay Time	—	800	—		$V_{\text{GE}} = \pm 15\text{V}$
$t_f$	Fall Time	—	190	—		See Fig.17 through Fig.21
$E_{\text{on}}$	Turn-On Switching Energy	—	41	—	mJ	
$E_{\text{off}}$	Turn-Off Switching Energy	—	56	—		
$E_{ts}$	Total Switching Energy	—	97	110		
$C_{\text{ies}}$	Input Capacitance	—	46800	—	pF	$V_{\text{GE}} = 0\text{V}$
$C_{\text{oes}}$	Output Capacitance	—	2920	—		$V_{\text{CC}} = 30\text{V}$
$C_{\text{res}}$	Reverse Transfer Capacitance	—	600	—		$f = 1\text{ MHz}$
$t_{rr}$	Diode Reverse Recovery Time	—	246	—	ns	$I_C = 500\text{A}$
$I_{rr}$	Diode Peak Reverse Current	—	144	—	A	$R_{G1} = 15\Omega$
$Q_{rr}$	Diode Recovery Charge	—	17655	—	$\mu\text{C}$	$R_{G2} = 0\Omega$
$di_{(\text{rec})}\text{M}/dt$	Diode Peak Rate of Fall of Recovery During $t_b$	—	1386	—	A/ $\mu\text{s}$	$V_{\text{CC}} = 360\text{V}$ $di/dt = 1300\text{A}/\mu\text{s}$



**Fig. 1** - Typical Load Current vs. Frequency  
 (Load Current =  $I_{RMS}$  of fundamental)



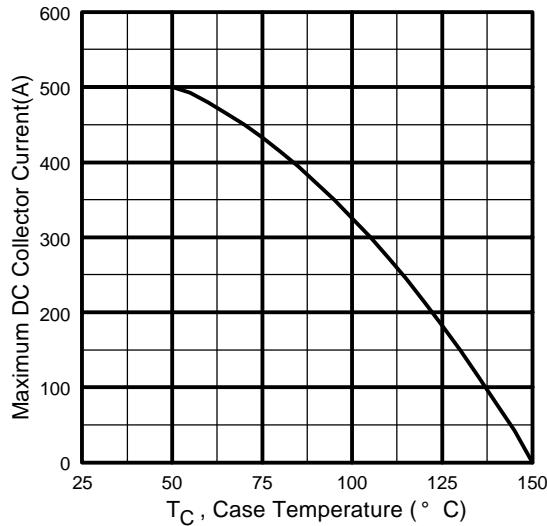
**Fig. 2** - Typical Output Characteristics  
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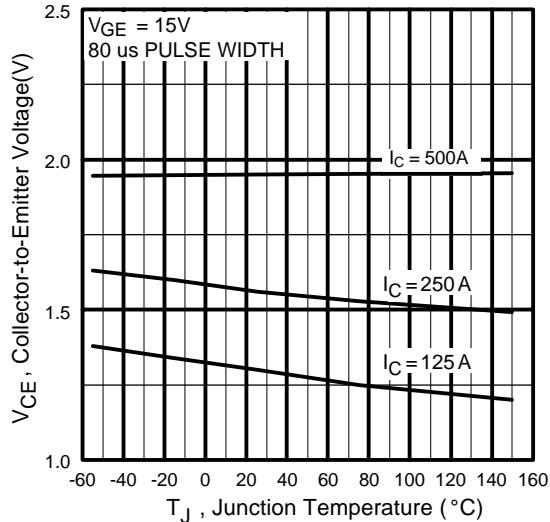
**Fig. 3** - Typical Transfer Characteristics  
 3

## GA500TD60U

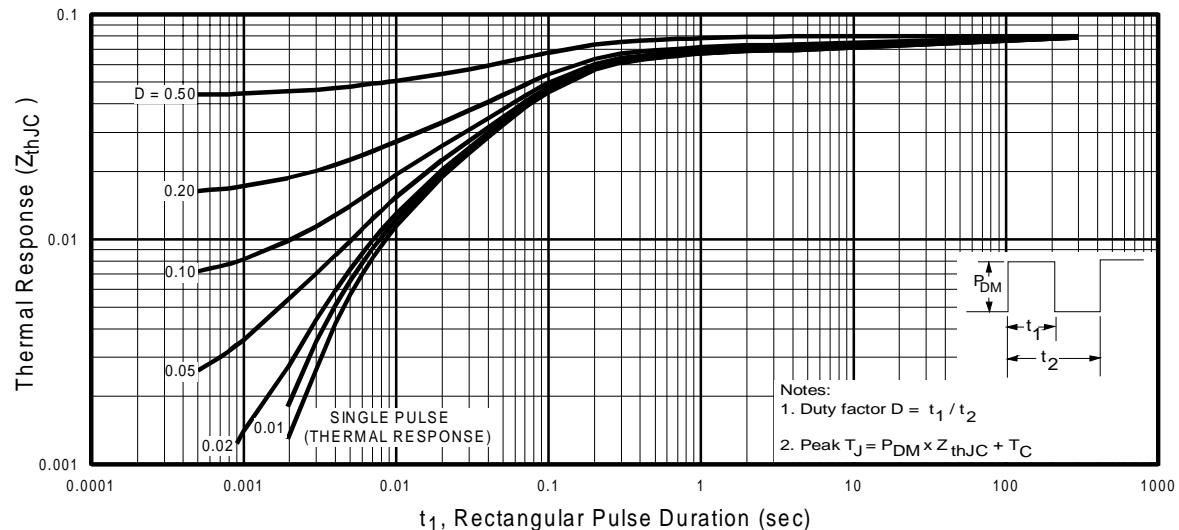
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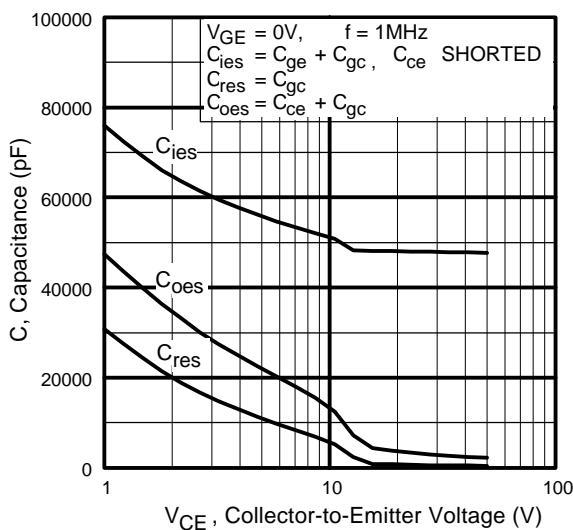
**Fig. 4 - Maximum Collector Current vs. Case Temperature**



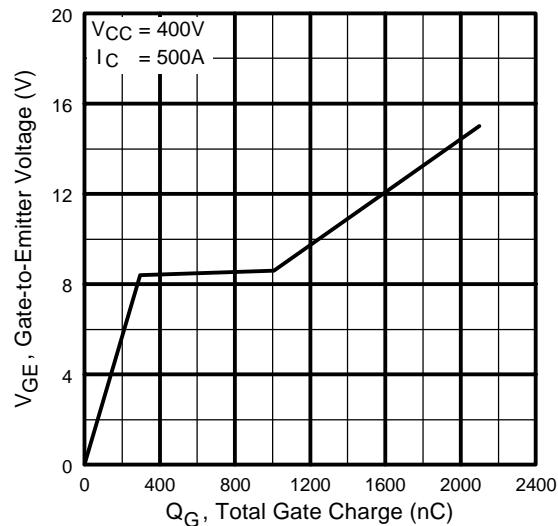
**Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature**



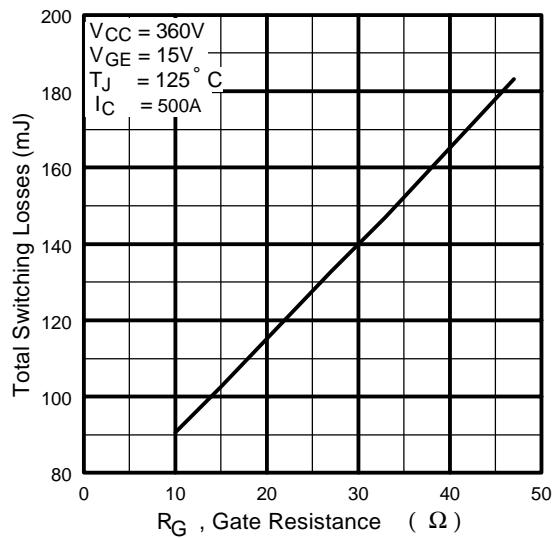
**Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



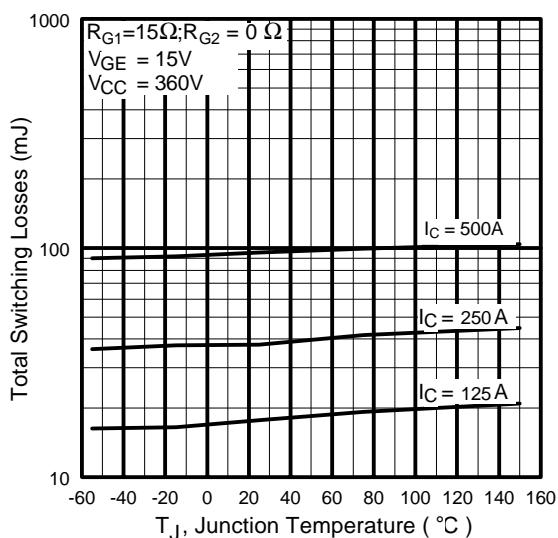
**Fig. 7** - Typical Capacitance vs.  
Collector-to-Emitter Voltage



**Fig. 8** - Typical Gate Charge vs.  
Gate-to-Emitter Voltage



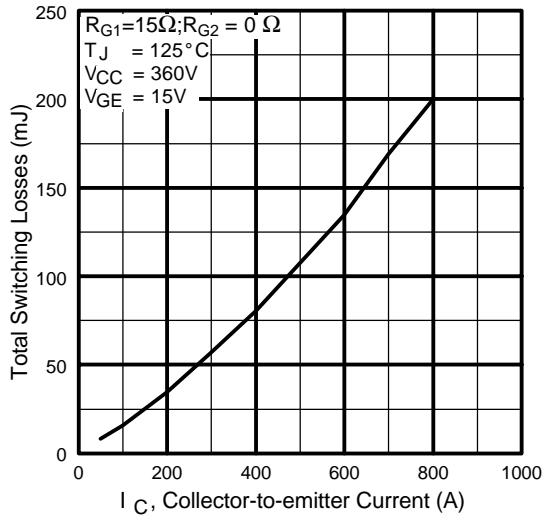
**Fig. 9** - Typical Switching Losses vs. Gate  
Resistance



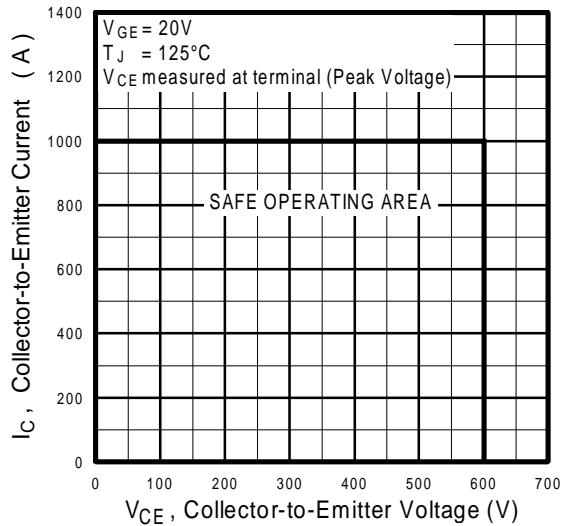
**Fig. 10** - Typical Switching Losses vs.  
Junction Temperature

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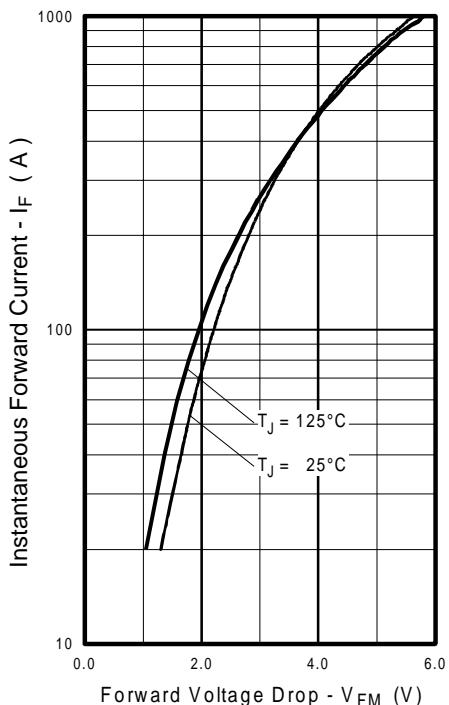
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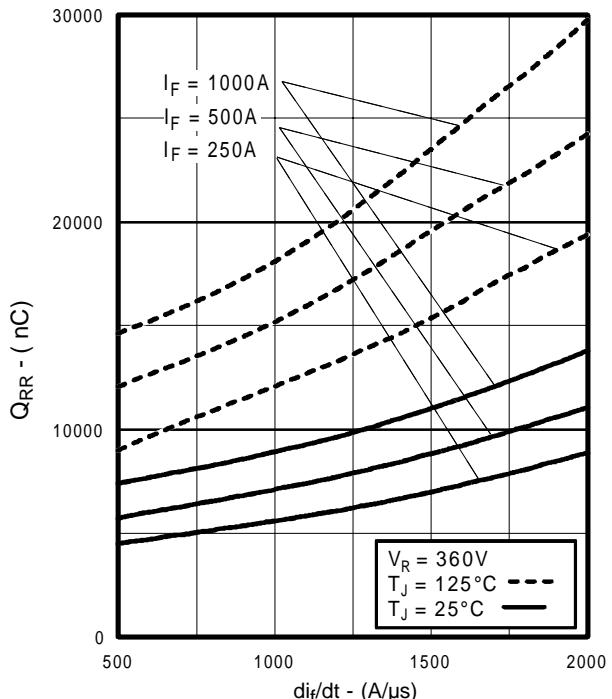
**Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current**



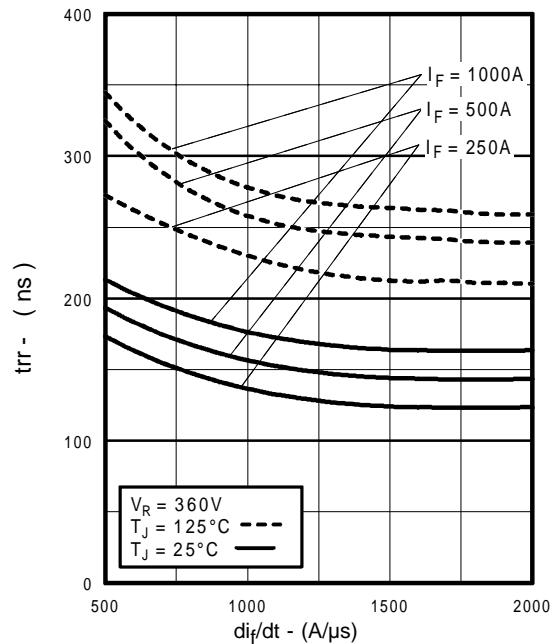
**Fig. 12 - Reverse Bias SOA**



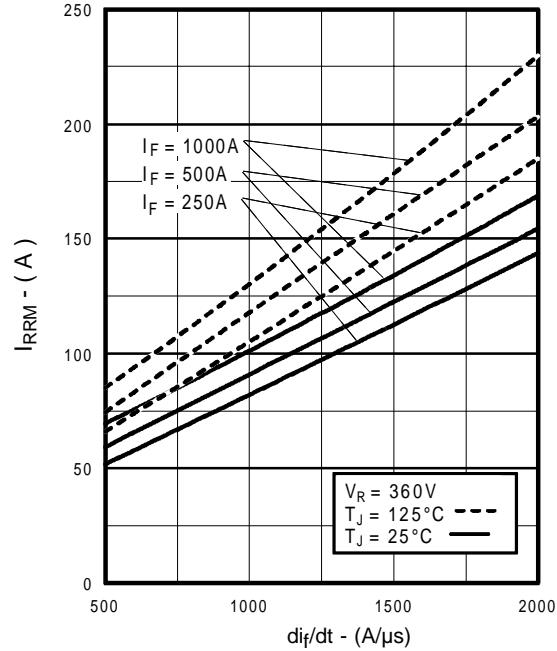
**Fig. 13 - Typical Forward Voltage Drop vs. Instantaneous Forward Current**



**Fig. 14 - Typical Stored Charge vs.  $di_f/dt$**



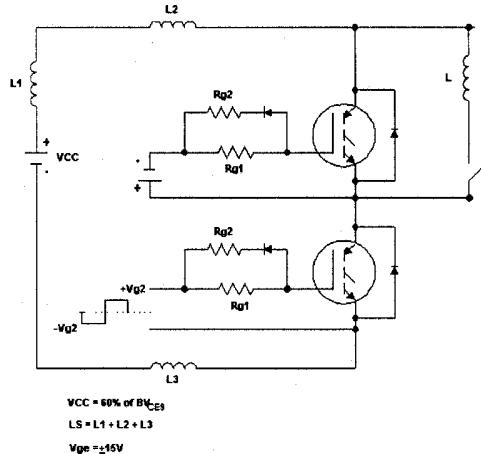
**Fig. 15** - Typical Reverse Recovery vs.  $di/dt$



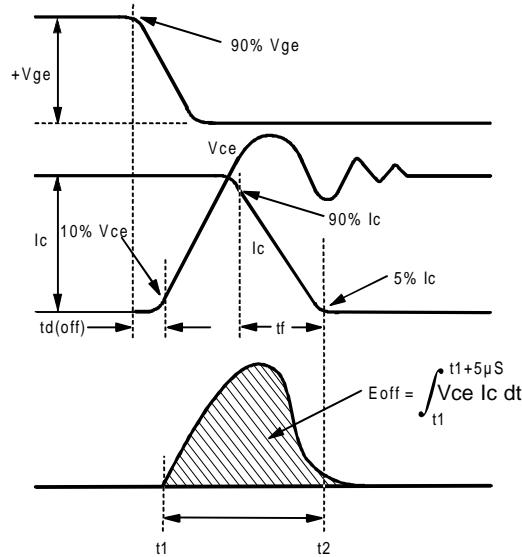
**Fig. 16** - Typical Recovery Current vs.  $di/dt$

## GA500TD60U

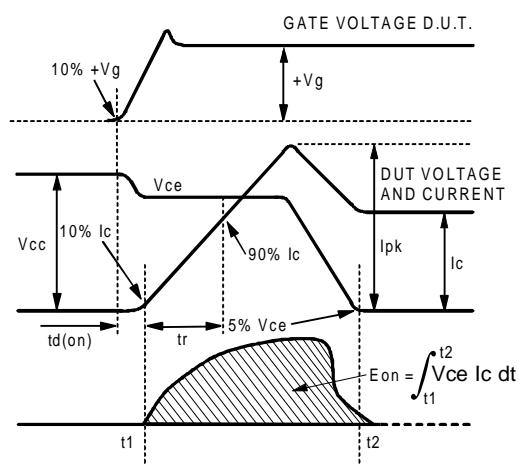
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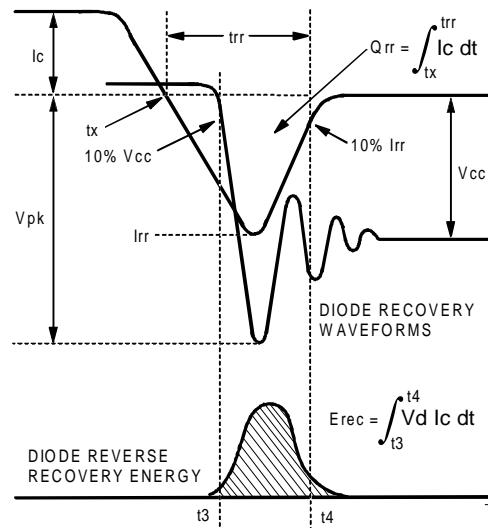
**Fig. 17** - Test Circuit for Measurement of  $I_{LM}$ ,  $E_{on}$ ,  $E_{off(diode)}$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$ ,  $t_d(on)$ ,  $t_r$ ,  $t_d(off)$ ,  $t_f$



**Fig. 18** - Test Waveforms for Circuit of Fig. 17, Defining  $E_{off}$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 19** - Test Waveforms for Circuit of Fig. 17, Defining  $E_{on}$ ,  $t_{d(on)}$ ,  $t_r$



**Fig. 20** - Test Waveforms for Circuit of Fig. 17, Defining  $E_{rec}$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$

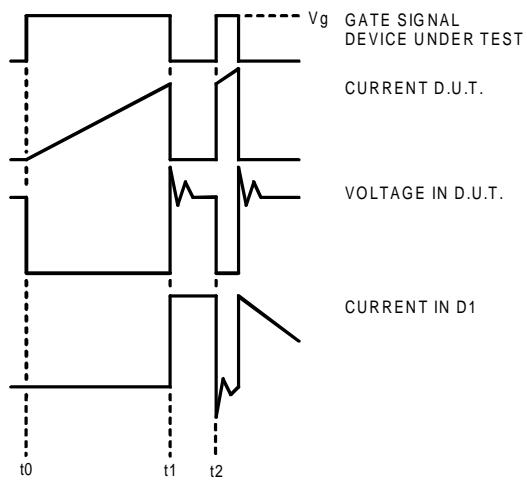


Figure 21. Macro Waveforms for Figure 17's Test Circuit

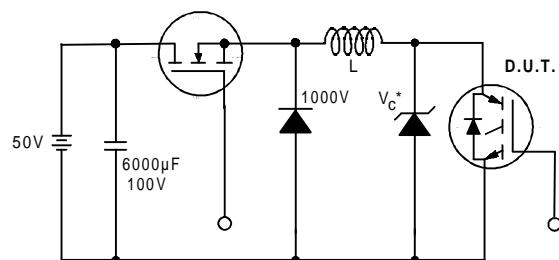


Figure 22. Clamped Inductive Load Test Circuit

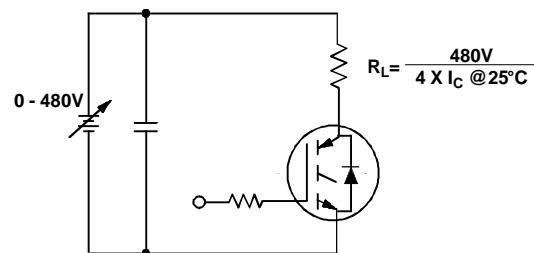


Figure 23. Pulsed Collector Current Test Circuit

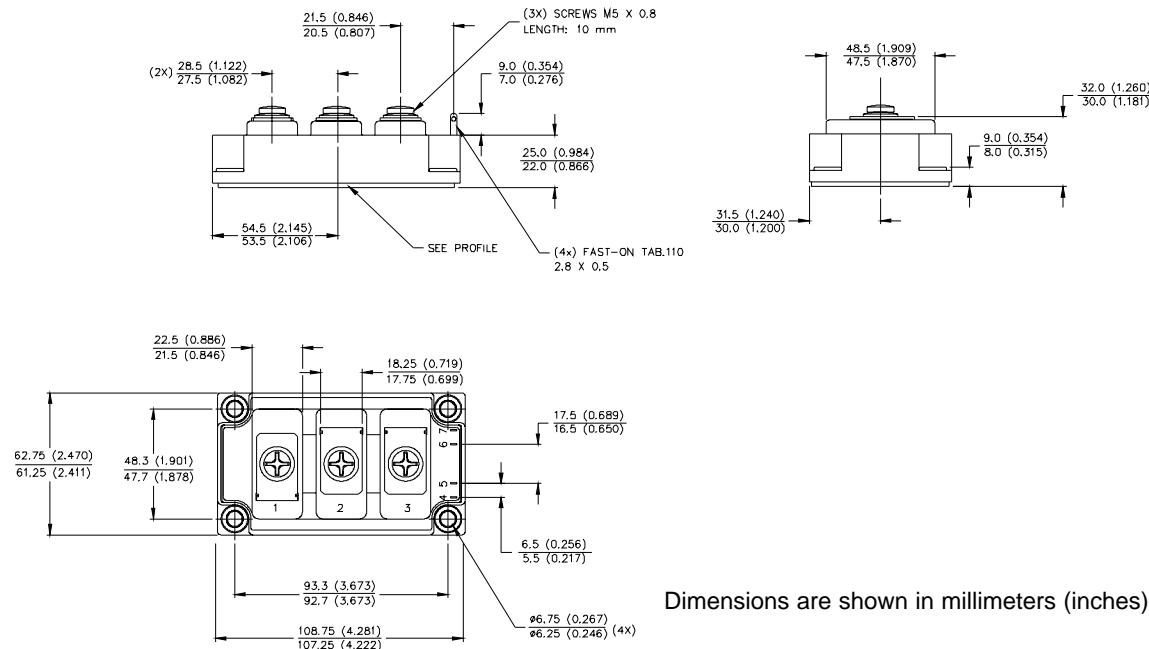
# GA500TD60U

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## Notes:

- ① Repetitive rating;  $V_{GE} = 20V$ , pulse width limited by max. junction temperature.
- ② See fig. 17
- ③ For screws M5x0.8
- ④ Pulse width 80 $\mu$ s; single shot.

## Case Outline — DOUBLE INT-A-PAK



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**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
**IR EUROPEAN REGIONAL CENTRE:** 439/445 Godstone Rd, Whyteleafe, Surrey CR3 OBL, UK Tel: ++ 44 (0)20 8645 8000

**IR CANADA:** 15 Lincoln Court, Brampton, Ontario L6T3Z2, Tel: (905) 453 2200

**IR GERMANY:** Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 (0) 6172 96590

**IR ITALY:** Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 011 451 0111

**IR JAPAN:** K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo 171 Tel: 81 (0)3 3983 0086

**IR SOUTHEAST ASIA:** 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994 Tel: ++ 65 (0)838 4630

**IR TAIWAN:** 16 Fl. Suite D. 207, Sec. 2, Tun Haw South Road, Taipei, 10673 Tel: 886-(0)2 2377 9936

*Data and specifications subject to change without notice. 10/00*

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